

 XB Connectivity	Doc. No.	SP-A0162-01	Page No.	1/9
	Date Issued	2015-04-06	Prepared by	Josephine
	Date revised	2018-11-23	checked by	Jay
Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: Board to Board Pitch 3.7mm X3700 Series Connector				

1. PSCOPE (适用范围)

This specification covers the performance, tests and quality requirements for the Board to Board 3.7mm Connector.(本规范涵盖了 Board to Board 3.7mm 连接器的性能、测试和质量要求。)
(作为板对板使用时)

2. PRODUCT DESCRIPTION (产品描述)

DESCRIPTION (描述)	Part Number (料号)
3.7mm 板对板连接器(MX3.7 503471),卧贴,公座	X3700WM-XXHF-LPSN
3.7mm 板对板连接器(MX3.7 503469),卧贴,母座	X3700WF-XXHF-LPSN

3. APPLICABLE DOCUMENT (适用文件)

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence. (XB Connectivity 下列文件构成本规范的一部分，在此规定的范围内。本规范要求与产品图纸有冲突时，以产品图纸为准。如果本规范的要求与参考文件发生冲突，应以本规范为准。)

- MIL-STD-1344A Test method for electrical connector (电子连接器测试方法)
- MIL-STD-202F Test method for electrical components (电子零件测试方法)
- EIA364 Test method for electrical components (电子零件测试方法)
- JIS C0051 Test method for electrical components (电子零件测试方法)
- MIL-G-45204C Specification for gold plating (镀金规格)
- IEC-512-3 IEC standard for current carrying capacity tests (IEC 电流测试标准)

 XB Connectivity Switch Connector	Doc. No.	SP-A0162-01	Page No.	2/9
	Date Issued	2015-04-06	Prepared by	Josephine
	Date revised	2018-11-23	checked by	Jay
Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: Board to Board Pitch 3.7mm X3700 Series Connector				

- QQ-N-290A Specification for nickel plating (镀镍规格)
- MIL-P-81728A Specification for tin/lead plating (镀锡铅规格)
- MIL-T-10727B Specification for tin plating (镀锡规格)
- UL498 UL standard for safety of attachment plug and receptacle (UL 安规要求标准)
- EN/ISO5961 Determination of total lead & cadmium content (总铅和总镉含量测定)
- EN1122 Determination of total lead & cadmium content (总铅和总镉含量测定)
- EN13346 Determination of heavy metals content (重金属含量测定)
- EPA3052 Determination of total lead & cadmium content (总铅和总镉含量测定)

4. REQUIREMENTS (XB CONNECTIVITY 要求)

4.1. Design and Structure (设计和结构)

Product shall be of the design, structure and physical dimensions specified on the applicable product drawing. (XB Connectivity 产品的设计、结构和物理尺寸参考所适用的产品图纸)

4.2. Materials/ Finish (材料/表面处理)

Materials used in the structure of product shall be as specified on the applicable product drawing. (产品结构中使用的材料参考所适用的产品图纸)

4.3. Ratings (额定功率)

XB Connectivity Item (项目)	Standard (标准)	
Rated Voltage (Maximum)额定电压	500V	AC
Rated Current (Maximum)额定电流	2A	
Operating temperature range工作温度范围	-40℃～+85℃ From -40 to +85 degree centigrade	
Storage Temperature Range储存温度范围	-40℃～+85℃ From -40 to +85 degree centigrade	

4.4. PACKAGING (包装)

Please refer to the packing drawing. 请参考产品包装图纸

4.5. MARKING (标识)

Manufacturer's name, industry recognized logo, or customer approved marks.

 XB Connectivity	Doc. No.	SP-A0162-01	Page No.	3/9
	Date Issued	2015-04-06	Prepared by	Josephine
	Date revised	2018-11-23	checked by	Jay
Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: Board to Board Pitch 3.7mm X3700 Series Connector				

标示制造商的名称，标识或客户认可的相关标志。

5. TEST STANDARD (测试标准)

Unless otherwise specified, the standard range of atmospheric conditions for making measurements and tests are as follows (除另有说明外，用以进行测量和测试的标准环境条件范围如下)

5.1 Ambient temperature (环境温度) : 5°C to 35°C

5.2 Relative humidity (相对湿度) : 45% to 85%

5.3 Air pressure (气压) : 86Kpa to 106Kpa

6. HOWEVER, IF DOUBTS ARISE CONCERNING JUDGMENTS. PERFORM UNDER THE FOLLOWING STANDARD CONDITIONS. (但是，如果对判决产生疑问，按照下列标准条件执行)

Temperature (温度) : 23±1°C.

Humidity (湿度) : 50%±2% RH.

Air Pressure (气压) : 86~106kPa

 XB Connectivity Switch Connector	Doc. No.	SP-A0162-01	Page No.	4/9
	Date Issued	2015-04-06	Prepared by	Josephine
	Date revised	2018-11-23	checked by	Jay
Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: Board to Board Pitch 3.7mm X3700 Series Connector				

7. PERFORMANCE AND TEST DESCRIPTION (性能和测试类型)

7.1 APPRARANANCE (外观)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	Appearance (外观)	Visual. (目视)	Should not have any flaw Scratch discoloration and crushed (无任何裂痕、刮伤、 污染和变形)

7.2 ELECTRICAL (电气)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	Low Level Contact Resistance (接触电阻)	EIA 364-23 Subject mated contacts assembled in housing to closed circuit of 100 mA max. at open circuit voltage of 20 mV max. (在开路最大电流 100mA 电压 20 mV 最 大下测量)	Iniital:90 m Ω maximum. (初始: 90 m Ω 最大)
2	Insulation Resistance (绝缘电阻)	MIL-STD-202, Method 302,Condition B Apply 250$\pm$10% volts DC between adjacent terminal or ground. (分别在相 邻端子或壳体之间施加 250V $\pm$ 10% DC 的电压持 续 1 分钟)	1000 M Ω minimum.
3	Dielectric Withstanding Voltage (耐电压)	MIL-STD-202, Method 301. Apply 150 Volts AC(RMS) between adjacent terminal or ground. Leakage current: 1mA Max. (分别在相邻端子或壳体之间施加 150V AC 1mA 的电流持续 1 分钟, 最大漏电电流 1mA)	No Breakdown (没有损坏)

 XB Connectivity Switch Connector	Doc. No.	SP-A0162-01	Page No.	5/9
	Date Issued	2015-04-06	Prepared by	Josephine
	Date revised	2018-11-23	checked by	Jay
Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: Board to Board Pitch 3.7mm X3700 Series Connector				

7.3 MECHANICAL (机械)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	Insertion Force(插入力)	EIA364-13 Insertion and withdrawal speed : 25mm/minute. (以每分钟 25mm 的速度沿轴向插入母座测量其插入力)	1.2N/Pin*Pin Max.
2	Extraction Force (拔出 力)	EIA364-13 Insertion and withdrawal speed : 25mm/minute. 以每分钟 25mm 的速度沿轴向从母座拔出测量其拔出力)	0.098N *Pin Min.
3	Durability (寿命测试)	EIA 364-09 Mate and Unmated connector for 30 cycles (沿轴向插拔 30 次)	Meets requirements of product appearance. Contact Resistance: 90 mΩ Max. after testing (符合产品外观要求, 测试后接触阻抗不大于 90mΩ)
4	Vibration Sinusoidal Low Frequency (低频正弦振动)	MIL-STD-202, Method 201. Subject mated connector to 10-55-10 Hz traversed in 1 minute at 1.5 mm amplitude 2 hours each of 3 mutually perpendicular plane, 10 mA. (对测试样品,在频率变化每分钟从10-55-10 Hz , 振幅 1.5 mm 条件下,在互相垂直的三个面上, 每个面 2 小时下测量, 电流 10 mA)	No electrical discontinuity greater than 1 μ sec (s) shall occur. Contact resistance:90 mΩ max. (不能超过 1 微秒瞬间断开, 接触阻抗: 90 mΩ 最大)
5	Mechanical Shock (机械冲击)	MIL-STD-202, Method 213 No discontinuities of 1 μS or longer duration when mated connectors are subjected to 490m/s ² half-sine shock pulses. Three shocks in each direction applied along three mutually shocks. (将对插后的连接器固定于冲击实验机上,中断不得大于或等于 1 μ s, 施加 490m/s ² 半正弦脉冲波, 沿 3 个互相垂直达的方向冲击)	Appearance (外观) : No Damage (没有损坏) Discontinuity (断讯) : 1 μ sec maximum. (不能超过 1微秒)

 XB Connectivity	Doc. No.	SP-A0162-01	Page No.	6/9
	Date Issued	2015-04-06	Prepared by	Josephine
	Date revised	2018-11-23	checked by	Jay
Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: Board to Board Pitch 3.7mm X3700 Series Connector				

7.4 ENVIRONMENTAL (环境)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	Thermal Shock (冷热冲击)	MIL-STD-202, Method 107D, condition A. Temperature range from -40°C to +85°C .Start from -40°C, after 30 min. change to +85°C; change time is no more than 30 seconds. Total 5 cycles. (温度变化范围: -40 ° C~ +85° C; 从 -40° C 开始, 30 分钟后换到+85° C; 转换时间不超过 30 秒; 共 5 个循环。)	No damage, Contact Resistance 90 mΩ max. (外观无损坏, 接触阻抗: 90 mΩ 最大)
2	Humidity (恒温恒湿)	MIL-STD-202, Method 103 Temperature (温度) :40±2°C Relative Humidity (相对湿度) : 90-95%; Duration (时间) :96 Hours	No damage, Contact Resistance 90 mΩ max.. Dielectric Strength should be OK. Insulation Resistance 1000MΩ min. (产品无损坏, 接触阻抗: 90 mΩ 最大; 耐电压测试 OK, 绝缘阻抗 1000MΩ 最小)
3	Solder ability (可焊性)	Immerse the solder pin of the connector in solder bath at 255±5°C for 3±0.5sec. After dipped the pin in the flux 5sec. (将端子脚浸入助焊剂中 5 秒, 然后将端子脚浸入 255±5°C 的锡炉中 3±0.5 秒)	Solder wetting: 95% of immersed area must show voids, Pin holes. (锡附着面积应超过浸入表面积的 95%以上)
4	High temperature (高温)	MIL-STD-202, Method 108. Subject product to 85±2°C for 96 hours Continuously. (产品置于 85 ± 2° C 连续 96 小时)	Contact resistance: 90 m Ω max. (接触阻抗 90 m Ω max.)

 XB Connectivity	Doc. No.	SP-A0162-01	Page No.	7/9
	Date Issued	2015-04-06	Prepared by	Josephine
	Date revised	2018-11-23	checked by	Jay
Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: Board to Board Pitch 3.7mm X3700 Series Connector				

5	Salt Spray (盐雾)	MIL-STD-202, Method 101 Condition B. Connectors to 35+/-2°C. Humidity:85%(R.H). PH value:6.5~7.2 and 5+/-1% salt condition for 24hours. After test, rinse the sample with water and recondition the room temperature for 1 hour test CR and IR. (将连接器放置在 35±2°C, 温度为 85% PH 值 6.5~7.2 和 5%浓度的实验箱内测试 24 小时, 测试后用水清洗样品, 放置室温 1 小时测试接触阻抗与绝缘阻抗)	Appearance: No Damage (外观无损坏) Contact Resistance 90 mΩ Max. (接触阻抗(末态) 90 mΩ Max.)
6	Resistance to Soldering heat (焊锡耐热性)	The contact of terminal shall be tested resistance to soldering heat in the following conditions. After Resistance to soldering heat test Contact Resistance. (端子应在下列条件下做耐吃锡性试验, 焊锡耐热性后试接触阻抗) In case of solder iron (2 time) 电烙铁(两次) Temperature 温度:≤350°C Time 时间: 5s+/-1s	Should not have any flaw scratch and crack. (无任何裂痕、刮伤和破裂)
7	IR-reflow (回流焊)	MIL-STD-202G method 210F Peak temperature time 260°C Max,10 sec or more. (峰值温度时间最高 260°C, 10 秒或以上) Duration : 2 cycles (过炉 2 次) Lead-Free Solder (无铅锡膏): Sn96.5Ag3Cu0.5 Refer to section 9 (请参阅第 9 条)	Should not have any flaw scratch and crack (无任何裂痕、刮伤和破裂) No visual damage to insulator. (绝缘体不得有严重变形)

 XB Connectivity	Doc. No.	SP-A0162-01	Page No.	9/9
	Date Issued	2015-04-06	Prepared by	Josephine
	Date revised	2018-11-23	checked by	Jay
Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: Board to Board Pitch 3.7mm X3700 Series Connector				

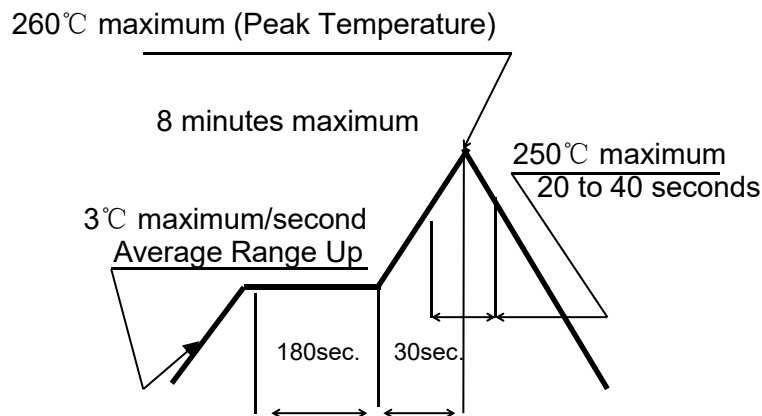
9. SOLDERING 焊接：

9.1. Wave soldering (波峰焊) : DIP Suggestions solder temperature at 260°C(500°F) max.5 seconds . DIP 型推荐焊接焊锡温度为 260°C (500°F) 最多 5 秒

9.2. Hand soldering (手焊) : Use a soldering iron of 30 watts controlled at 350°C approximately 5 seconds. while applying solder.

使用 30W 烙铁控制温度在 350°C,焊接时长约 5 秒

9.3. Reflow soldering profile(回炉焊):When the maximum temperature of the reflow furnace is 260 °C and the temperature is 260 °c. 10 seconds MAX. (reference) SMT 型回焊炉最高温度为 260°C，温度为 260°C时，最长时间不超过 10 秒 (如图)



(Preheat Temperature预热温度: 150~200°C Maximum.)

Temperature Condition Graph.温度状态图

(Temperature on Board Pattern Side)

Requirement要求: No physical damaged or plastic melting.: 无物理损伤或塑料熔化

 XB Connectivity Switch Connector	Doc. No.	X-A0162-19	Page No.	1/9
	Date Issued	2020-04-06	Prepared by	Josephine
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Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: 3.7mm Pitch X3700 Series Connector				

1. SCOPE (适用范围)

This specification covers the performance , tests and quality requirements for the 3.7mm series wire to board connector. (XB Connectivity 本规范涵盖了盖 3.7mm 系列线对板连接器性能、测试和质量要求)
(作线对板使用时)

2. PRODUCT DESCRIPTION (产品描述)

DESCRIPTION (描述)	Part Number (料号)
3.7mm 板对板连接器(MX3.7 503471),卧贴,公座	X3700WM-XXHF-LPSN
3.7mm 板对板连接器(MX3.7 503469),卧贴,母座	X3700WF-XXHF-LPSN
3.7mm 板对板连接器(MX3.7)HSG	X3700H-XX-PT
3.7mm 板对板连接器(MX3.7)端子,磷铜先冲后镀	X3700T-PXX

3. APPLICABLE DOCUMENT (适用文件)

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence. (XB Connectivity 下列文件构成本规范的一部分，在此规定的范围内。本规范要求与产品图纸有冲突时，以产品图纸为准。如果本规范的要求与参考文件发生冲突，应以本规范为准。)

4. REQUIREMENTS (要求)

4.1. Design and Structure (设计和结构)

 XB Connectivity Switch Connector	Doc. No.	X-A0162-19	Page No.	2/9
	Date Issued	2020-04-06	Prepared by	Josephine
	Date revised	2020-11-23	checked by	Jay
Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: 3.7mm Pitch X3700 Series Connector				

Product shall be of the design, structure and physical dimensions specified on the applicable product drawing. (XB Connectivity 产品的设计、结构和物理尺寸参考所适用的产品图纸)

4.2. Materials/ Finish (材料/表面处理)

Specification 规格内容		Materials 材质	Disposal of Surface 表面处理
Terminal 端子		Phosphor Bronze 磷铜	Tin Plated: 70μ. Nickel: Over 30μ"
Housing 胶壳		PA66	UL 94V-2/UL94V-0
Wafe 针座	Base	LCP	UL 94V-2/UL94V-0
	PIN	Phosphor Bronze 磷铜	Over Tin 70μ" Plated ; Over 30μ" Nickel

Please Refer to the Project drawing for the above Specification. (上述参数请以工程图为准)

4.3. Ratings (额定功率)

XB Connectivity Item (项目)	Standard (标准)	
Rated Voltage (Maximum) 额定电压	500V	AC/DC
Rated Current (Maximum) 额定电流	2A	
Ambient temperature Range 使用温度范围	-40℃ ~ +85℃ From -40 to +85 degree centigrade	
Applicable wire insulation O.D 适用线径	AWG 26#~28#	
NOTE备注 : Including terminal temperature rise 升温时含端子		

5. TEST STANDARD (测试条件)

5.1 Unless otherwise specified, the standard range of atmospheric conditions for making measurements and tests are as follows (除另有说明外，用以进行测量和测试的标准环境条件范围如下)

Ambient temperature (环境温度) : 5℃ to 35℃

Normal humidity (正常湿度) : 45% to 85%

Air pressure (气压) : 86Kpa to 106Kpa

5.2 However if doubt arises on the decision based on the measured Values under the above-mentioned Conditions. The following conditions shall be employed: (但是在对判定产生疑问时,按下述状态实施)

 XB Connectivity Switch Connector	Doc. No.	X-A0162-19	Page No.	3/9
	Date Issued	2020-04-06	Prepared by	Josephine
	Date revised	2020-11-23	checked by	Jay
Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: 3.7mm Pitch X3700 Series Connector				

Temperature (温度) : $20\pm 2^{\circ}\text{C}$

Relative humidity (相对湿度) : $65\pm 5\%$

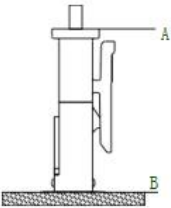
Air pressure (气压) : 86Kpa to 106Kpa

8. PERFORMANCE AND TEST DESCRIPTION (性能和测试类型)

8.1 APPEARANCE (外观)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	Appearance (外观)	Visual. (目视)	Should not have any flaw Scratch discoloration and crushed (无任何裂痕、刮伤、 污染和变形)

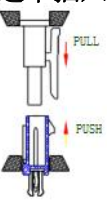
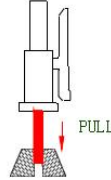
8.2 ELECTRICAL (电气)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	contact resistance (接触阻抗)	Based upon EIA-364-06A. Mate connectors, measure by dry circuit, 20mV MAX, 10mA. (公母配合, 开放电压 20mV 以下, 电流 10mA 检测连接器 A~B 区) 	Initial (初始) : 10 milliohms Max. After Test (测试后) : 20 milliohms Max.
2	Insulation Resistance (绝缘阻抗)	Based upon EIA-364-21B/MIL-STD-202 Method 302 Cond. B Mate connectors, apply 500V DC between adjacent terminal or ground. (公母配合, 在相邻端子, 端子与地片之间, 使用 500V 的直流电, 检测连接器)	1000 MΩ min.

 XB Connectivity Switch Connector	Doc. No.	X-A0162-19	Page No.	4/9
	Date Issued	2020-04-06	Prepared by	Josephine
	Date revised	2020-11-23	checked by	Jay
Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: 3.7mm Pitch X3700 Series Connector				

3	Dielectric strength (耐电压)	Based upon EIA-364-20A/MIL-STD-202 Method 301 Mate connectors, apply 1000V AC for 1 minute between adjacent terminal or ground. (公母配合, 在相邻端子, 端子与地片之间, 使用 1000V 的交流电 1 分钟, 检测连接器)	There shall be no breakdown. (无击穿、闪烁现象)
4	Contact resistance on crimped portion (铆线后端子接触阻抗)	Crimp the applicable wire on to the terminal measure by dry circuit 20mV MAX, 10mA. (铆线后之端子, 开放电压 20mV 以下, 电流 10mA 检测连接器)	10 milliohms

8.3 MECHANICAL (机械)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	Insertion & Retention Force (插拔力)	Insert and withdraw Connectors at the speed rate of 25.4±3mm/minute. (以每分钟 25.4±3mm 的速率插入和拔出) 	Refer to paragraph 6 参照第 10 项
2	Terminal/ Housing Retention Force (端子保持力)	Apply axial pull out force at the speed rate of 25.4±3mm/minute on the terminal assembled in the housing. (以每分钟 25.4±3mm 的速率, 将端子从 Housing 内轴向拔出的力量。) 	24.5N {2.5kgf}Min.
3	Terminal Insertion Force (端子插入力)	Insert the crimped terminal into the housing. (铆线后之端子插入 Housing 所需最大力量)	14.7N {1.5kgf} Max.



XB Connectivity

Doc. No.

X-A0162-19

Page No.

5/9

Date Issued

2020-04-06

Prepared by

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Product Specification

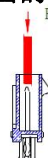
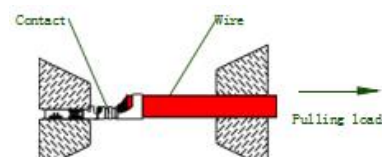
Rev. No.

01

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Mei Chen

Title: 3.7mm Pitch X3700 Series Connector

4	PIN Retention Force (PIN 针保持力)	Apply axial push force at the speed rate of 25.4±3mm/minute. (以每分 25.4±3mm 的速率, 将 PIN 针从 Wafer 内轴向拔出的力量) 	13.7N {1.4kgf} min.			
5	Tensile strength (Crimped connections) (端子压着强度)	Fix the crimped terminal, apply axial pull out force on the wire. (Do not crimp insulation part). (固定铆线后的端子, 使电线与端子分离时所需的最小力量) 	AWG	#20	#22	#24
			Spec. kgf. Min.	6.0	4.0	2.0
			Note> As for unspecified wire sizes in this specification define values with clients			
6	Repeated Insertion/Withdrawal (重复插拔)	When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute. (以每分钟不超过 10 次的速率, 将公母插拔 30 次.)	Contact Resistance (接触阻抗) : 20 milliohms Max.			
7	Vibration (耐振动性)	Based upon EIA-364-28B/MIL-STD-202 Method 213B Cond.A Amplitude (振幅) : 1.5mm P-P Sweep time (频率) : 10~55~10 HZ in 1 minute Duration (持续时间) : 2 hours in each X.Y.Z axials. (每轴向 2 小时)	Appearance 外观: No Damage 无异状 Contact Resistance 接触阻抗: 20 milliohms Max. Discontinuity 瞬断: 1 micro- second Max.			
8	Shock (耐冲击性)	Based upon EIA-364-27B/MIL-STD-202 Method 213B Cond.A Pulse width (冲击时间) : 11 msec., Waveform (波形) : half sine, 490m/s2{50G}, 3 strokes in each X.Y.Z. axes. (加速度最大 50G, 沿 3 个互相垂直达的方向)	Appearance 外观: No Damage 无异状 Contact Resistance 接触阻抗: 20 milliohms Max. Discontinuity 瞬断: 1 micro- second Max.			

 XB Connectivity Switch Connector	Doc. No.	X-A0162-19	Page No.	6/9
	Date Issued	2020-04-06	Prepared by	Josephine
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Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: 3.7mm Pitch X3700 Series Connector				

8.4 ENVIRONMENTAL (环境)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	Temperature Rise (温升测试)	Carrying rated current load. (UL 1977) (公母对插后, 在通过额定电流下, 所测定的温度)	30°C Max.
2	Heat Resistance (耐热性)	Based upon MIL-STD-202 Method 108A Cond.A 85±2°C, 96 hours.	Appearance 外观: No Damage 无异状 Contact Resistance 接触阻抗: 20 milliohms Max.
3	Cold Resistance (耐寒性)	Based upon EIA-364-105 -25±5°C, 96 hours.	Appearance 外观: No Damage 无异状 Contact Resistance 接触阻抗: 20 milliohms Max.
4	Humidity (耐湿性)	Based upon EIA-364-31A/MIL-STD-202 Method 103B Cond.B Temperature (温度): 40±2°C Relative Humidity (湿度): 90~95% Duration (持续时间): 96 hours	Appearance 外观: No Damage 无异状 Contact Resistance 接触阻抗: 20 milliohms Max. Insulation Resistance 绝缘阻抗: 1000 MΩ min.
5	Temperature Cycling (温度变化)	Based upon EIA-364-32B 5 cycles of: a) -55°C 30 minutes. b) +85°C 30 minutes. (从-55°C持续 30 分钟升至+85°C持续 30 分钟, 循环 5 次)	Appearance 外观: No Damage 无异状 Contact Resistance 接触阻抗: 20 milliohms Max.
6	Salt Spray (盐水喷雾)	Based upon EIA-364-26A/MIL-STD-202 Method 101D Cond.B 24±1 hours exposure to a salt spray from the 5±1% solution at 35±2°C. (在温度 35±2°C, 盐水浓度 5±1%下, 盐水喷雾 24±1 小时) 注: 此项测试只针对先冲后镀端	Appearance 外观: No Damage 无异状 Contact Resistance 接触阻抗: 20 milliohms Max.
7	Solder-ability (焊锡附着性)	Based upon EIA-364-52 Soldering Time 焊接时间: 3±0.5second. Solder Temperature 焊接温度: 245±5°C.	Immersed area must show no voids, pin holes. 浸渍面积需95%以上

 XB Connectivity Switch Connector	Doc. No.	X-A0162-19	Page No.	7/9
	Date Issued	2020-04-06	Prepared by	Josephine
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Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: 3.7mm Pitch X3700 Series Connector				

8	Solder- Resistance (焊锡耐热性)	Based upon EIA-364-56A Soldering time 焊接时间:3~5 sec Solder Temperature 焊接温度:250±5℃.	Appearance 外观: No Damage 无异状
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9. PACKAGING 包装

Please refer to the packing drawing. 请参考产品包装图纸

10. INSERTION/WITHDRAWAL FORCE 综合插入力及拔出力:

PIN 数 No. of CKT	初次插入力(最大值) First Insertion (kgf Max.)	30 次拔出力(最小值) 30 th Withdrawal (kgf Min.)	PIN 数 No. of CKT	初次插入力(最大值) First Insertion (kgf Max.)	30 次拔出力(最小值) 30 th Withdrawal (kgf Min.)
Single	1.0	0.35	7	5.6	1.75
2	1.6	0.50	8	6.4	2.00
3	2.4	0.75	9	7.2	2.25
4	3.2	1.00	10	8.0	2.50
5	4.0	1.25	11	8.8	2.75
6	4.8	1.50	12	9.6	3.00
DOUBLE ROW (双排)					

 XB Connectivity	Doc. No.	X-A0162-19	Page No.	8/9
	Date Issued	2020-04-06	Prepared by	Josephine
	Date revised	2020-11-23	checked by	Jay
Product Specification	Rev. No.	01	Approved by	Mei Chen
Title: 3.7mm Pitch X3700 Series Connector				

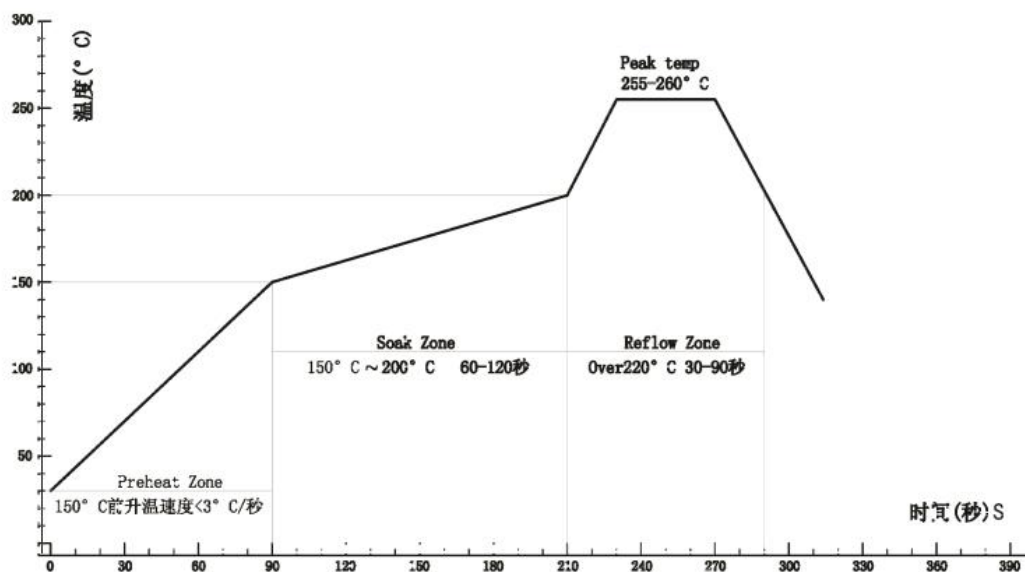
2*02	3.2	1.00	2*08	12.8	4.00
2*03	4.8	1.50	2*09	14.4	4.50
2*04	6.4	2.00	2*10	16.0	5.00
2*05	8.0	2.50	2*11	17.6	5.50
2*06	9.6	3.00	2*12	19.2	6.00
2*07	11.2	3.50			

11. SOLDERING 焊接：

11.1. Wave soldering(波峰焊)：DIP Suggestions solder temperature at 260°C(500°F) max.5 seconds . DIP 型推荐焊接焊锡温度为 260°C (500°F) 最多 5 秒

11.2. Hand soldering (手焊)：Use a soldering iron of 30 watts controlled at 350°C approximately 5 seconds. while applying solder.
使用 30W 烙铁控制温度在 350°C,焊接时长约 5 秒

11.3. Reflow soldering profile (回炉焊)：When the maximum temperature of the reflow furnace is 260 °C and the temperature is 260 °c. 10 seconds MAX. (reference) SMT 型回焊炉最高温度为 260°C，温度为 260°C时，最长时间不超过 10 秒（如图）



 XB Connectivity	Doc. No.	X-A0162-19	Page No.	9/9
	Date Issued	2020-04-06	Prepared by	Josephine
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Rev.	Description	Date revised	Created/ Revised by
01	New Release	2022/05/20	Josephine Lin